Product Change Notification

Change Notification #: 117623 - 01

Change Title: Stratix® II, Stratix® II GX and Arria® GX Products in Flip Chip,
PCN 117623-01, Product Design, Product Material
Leaded Bumps (1st level interconnect)
Package Status Update
Reason for Revision: Updated Table 1 Status and Recommended Actions for Stratix II, Stratix II GX, and Arria GX.

Date of Publication: December 11, 2020

Key Characteristics of the Change:

Product Design, Product Material

Forecasted Key Milestones:

Table 1

Product Family	**Status of Replacement Package with Leadfree SnAg Bumps (ROHS 6 "G" suffix OPN)**	**Estimated Completion**
Stratix II	All parts numbers in these product families **are being discontinued.** Please refer to the discontinuance notification **PDN2041** issued on December 4, 2020. Link: https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/pdn2041.pdf	Not applicable
Stratix II GX		
Arria GX* *except for parts in the next row		
Arria GX EP1AGX50C/60C in F484 pins. Part numbers: • EP1AGX50CF484C6N • EP1AGX50CF484I6N • EP1AGX60CF484C6N • EP1AGX60CF484I6N • EP1AGX50CF484C6	Due to technical limitations, there is no plan to offer replacement "G" products with leadfree bumps. Product Discontinuance **PDN2018** issued for these five (5) part numbers: https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/pdn2018.pdf (copy and paste into browser)	Not applicable

Description of Change to the Customer:

This revision is the same one communicated as a follow up to ADV2019, issued on December 4, 2020

Reason for Revision: Updated Table 1 Status and Recommended Actions for Stratix II, Stratix II GX, and Arria GX. These products are now being discontinued via PDN2041 issued in December 4, 2020.

This is a supplemental notification to advisories ADV1828 and ADV2001, to address Stratix® II, Stratix® II GX and Arria® GX products with leaded (SnPb) bumps as 1st level interconnect (die-to-substrate connection).

Intel will continue to supply Stratix® II, Stratix® II GX and Arria® GX products with leaded bumps (in both leadfree solder ball "N" suffix part numbers and leaded solder ball part numbers) until the ROHS6 package qualification has been completed and further notification about product availability is provided.

Customer Impact of Change and Recommended Action:

Please refer to PDN2041 for details on the discontinuance of Stratix II, Stratix II GX, and Arria GX parts.

A selected number for Arria GX (listed in Table 1) was already applied with a discontinuance notification via PDN2018 issued in May 22, 2020: https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/pdn2018.pdf.

Products Affected / Intel Ordering Codes:

The link below contains the list of affected part numbers (OPNs) with the corresponding leadfree bumps conversion status.
https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/adv2019-opn-list.xlsx

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
June 4, 2020	00	Originally Published PCN
December 11, 2020	01	Updated Table 1 Status and Recommended Actions for Stratix II, Stratix II GX, and Arria GX. These products are now being discontinued via PDN2041 issued in December 4, 2020.

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117623 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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